LMT01 0.5°C Accurate 2-Pin Digital Output Temperature Sensor With Pulse Count Interface

1 Features

• High Accuracy Over –50°C to 150°C Wide Temperature Range
  – -20°C to 90°C: ±0.5°C (Maximum)
  – 90°C to 150°C: ±0.625°C (Maximum)
  – -50°C to -20°C: ±0.7°C (Maximum)
• Precision Digital Temperature Measurement Simplified in a 2-Pin Package
• Pulse Count Current Loop Easily Read by Processor. Number of Output Pulses is Proportional to Temperature With 0.0625°C Resolution
• Communication Frequency: 88 kHz
• Conversion Current: 34 µA
• Continuous Conversion Plus Data-Transmission Period: 100 ms
• Floating 2-V to 5.5-V (VP–VN) Supply Operation With Integrated EMI Immunity
• Multiple 2-Pin Package Offerings: TO-92/LPG (3.1 mm × 4 mm × 1.5 mm) – ½ the Size of Traditional TO-92 and WSON With Wettable Flanks

2 Applications

• Digital Output Wired Probes
• White Goods
• HVAC
• Power Supplies
• Battery Management

3 Description

The LMT01 device is a high-accuracy, 2-pin temperature sensor with an easy-to-use pulse count current loop interface, which makes it suitable for onboard and offboard applications in automotive, industrial, and consumer markets. The LMT01 digital pulse count output and high accuracy over a wide temperature range allow pairing with any MCU without concern for integrated ADC quality or availability, while minimizing software overhead. TI’s LMT01 device achieves a maximum ±0.5°C accuracy with very fine resolution (0.0625°C) over a temperature range of -20°C to 90°C without system calibration or hardware and software compensation.

The LMT01’s pulse count interface is designed to directly interface with a GPIO or comparator input, thereby simplifying hardware implementation. Similarly, the LMT01’s integrated EMI suppression and simple 2-pin architecture makes it suitable for onboard and offboard temperature sensing in a noisy environment. The LMT01 device can be easily converted into a two-wire temperature probe with a wire length up to two meters. See LMT01-Q1 for the automotive qualified version.

Device Information

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>PACKAGE</th>
<th>BODY SIZE (NOM)</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMT01LPG</td>
<td>TO-92</td>
<td>4.00 mm × 3.15 mm</td>
</tr>
<tr>
<td>LMT01DQX</td>
<td>WSON</td>
<td>1.70 mm × 2.50 mm</td>
</tr>
</tbody>
</table>

(1) For all available packages, see the orderable addendum at the end of the data sheet.

2-Pin IC Temperature Sensor

Typical units plotted in center of curve.
Table of Contents

1 Features ........................................................................ 1
2 Applications ................................................................... 1
3 Description ..................................................................... 1
4 Revision History .......................................................... 2
5 Pin Configuration and Functions .................................... 3
6 Specifications .................................................................. 4
   6.1 Absolute Maximum Ratings ........................................ 4
   6.2 ESD Ratings ............................................................. 4
   6.3 Recommended Operating Conditions ......................... 4
   6.4 Thermal Information ................................................ 4
   6.5 Electrical Characteristics .......................................... 5
   6.6 Electrical Characteristics - TO-92/LPG Pulse Count to
      Temperature LUT ..................................................... 6
   6.7 Electrical Characteristics - WSON/DQX Pulse Count to
      Temperature LUT .................................................... 7
   6.8 Switching Characteristics .......................................... 7
   6.9 Timing Diagram ....................................................... 8
   6.10 Typical Characteristics ............................................ 9
7 Detailed Description .................................................... 12
   7.1 Overview ............................................................... 13
   7.2 Functional Block Diagram ......................................... 13
   7.3 Feature Description ................................................ 13
   7.4 Device Functional Modes ......................................... 16
8 Application and Implementation ..................................... 17
   8.1 Application Information ........................................... 17
   8.2 Typical Application ................................................ 18
   8.3 System Examples .................................................. 20
9 Power Supply Recommendations ..................................... 22
10 Layout ........................................................................ 23
   10.1 Layout Guidelines .................................................. 23
   10.2 Layout Example ..................................................... 23
11 Device and Documentation Support ............................... 24
   11.1 Receiving Notification of Documentation Updates .......... 24
   11.2 Community Resources ............................................ 24
   11.3 Trademarks ........................................................... 24
   11.4 Electrostatic Discharge Caution ............................... 24
   11.5 Glossary ............................................................... 24
12 Mechanical, Packaging, and Orderable
   Information ................................................................. 24

4 Revision History

Changes from Revision C (June 2017) to Revision D Page

• Added device stamp to the TO-92 pinout top view ......................................................... 3
• Changed the TO-92S pin numbers in the Pin Functions.................................................. 3

Changes from Revision B (April 2017) to Revision C Page

• Removed Electrical Characteristics: WSON/DQX table; Combined the LPG and DQX Electrical Characteristics tables together ......................................................... 5
• Changed IOL maximum value from: 39 µA to: 40 µA ...................................................... 5
• Changed leakage value from: 1 µA to 3.5 µA ............................................................... 5
• Moved the thermal response time parameters to the Electrical Characteristics table ......................................................... 5
• Added Missing Cross References .................................................................................. 13

Changes from Revision A (June 2015) to Revision B Page

• Added new WSON/DQX package throughout data sheet ............................................... 1
• Changed updated package information. ........................................................................ 3
• Added Electrical Characteristics - WSON/DQX Pulse Count to Temperature LUT .......... 7
• Added -40 for Sample Calculations Table .................................................................... 14
• Added missing cross reference .................................................................................... 15

Changes from Original (June 2015) to Revision A Page

• Added full datasheet. ................................................................................................. 1
• Added clarification note. ......................................................................................... 1

7 Detailed Description

7.1 Overview ............................................................... 13
## 5 Pin Configuration and Functions

### Pin Functions

<table>
<thead>
<tr>
<th>PIN</th>
<th>TYPE</th>
<th>DESCRIPTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>VP</td>
<td>2</td>
<td>Input, Positive voltage pin; may be connected to system power supply or bias resistor.</td>
</tr>
<tr>
<td>VN</td>
<td>1</td>
<td>Output, Negative voltage pin; may be connected to system ground or a bias resistor.</td>
</tr>
</tbody>
</table>

### Diagrams

- **DOX Package**
  - 2-Pin WSON
  - Bottom View

- **LPG Package**
  - 2-Pin TO-92
  - Top View
6 Specifications

6.1 Absolute Maximum Ratings

See (1)(2).

<table>
<thead>
<tr>
<th></th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Voltage drop (VP – VN)</td>
<td>−0.3</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>Storage temperature, T_{stg}</td>
<td>−65</td>
<td>175</td>
<td>°C</td>
</tr>
</tbody>
</table>

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) Soldering process must comply with Reflow Temperature Profile specifications. Refer to www.ti.com/packaging.

6.2 ESD Ratings

<table>
<thead>
<tr>
<th>Value</th>
<th>ELECTROSTATIC DISCHARGE</th>
<th>VALUE</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{(ESD)}$</td>
<td>Electrostatic discharge</td>
<td>$\pm2000$</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001$^{(1)}$</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>Charged-device model (CDM), per JEDEC specification JESD22-C101$^{(2)}$</td>
<td>$\pm750$</td>
<td></td>
</tr>
</tbody>
</table>

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

<table>
<thead>
<tr>
<th></th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Free-air temperature</td>
<td>−50</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>Voltage drop (VP – VN)</td>
<td>2</td>
<td>5.5</td>
<td>V</td>
</tr>
</tbody>
</table>

6.4 Thermal Information

<table>
<thead>
<tr>
<th>THERMAL METRIC$^{(1)}$</th>
<th>LMT01</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>DQX (WSON)</td>
</tr>
<tr>
<td></td>
<td>2 PINS</td>
</tr>
<tr>
<td>$R_{\text{jua}}$</td>
<td>Junction-to-ambient thermal resistance</td>
</tr>
<tr>
<td>$R_{\text{juc(top)}}$</td>
<td>Junction-to-case (top) thermal resistance</td>
</tr>
<tr>
<td>$R_{\text{jub}}$</td>
<td>Junction-to-board thermal resistance</td>
</tr>
<tr>
<td>$\psi_{\text{jt}}$</td>
<td>Junction-to-top characterization parameter</td>
</tr>
<tr>
<td>$\psi_{\text{jb}}$</td>
<td>Junction-to-board characterization parameter</td>
</tr>
</tbody>
</table>

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.
6.5 Electrical Characteristics

Over operating free-air temperature range and operating VP-VN range (unless otherwise noted).

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>ACCURACY</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Temperature accuracy (1)(2)</td>
<td>VP – VN of 2.15 V to 5.5 V</td>
<td>150°C</td>
<td>-0.625</td>
<td>0.625</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td></td>
<td>125°C</td>
<td>-0.625</td>
<td>0.625</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td></td>
<td>120°C</td>
<td>-0.625</td>
<td>0.625</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td></td>
<td>110°C</td>
<td>-0.5625</td>
<td>0.5625</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td></td>
<td>100°C</td>
<td>-0.5625</td>
<td>0.5625</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td></td>
<td>90°C</td>
<td>-0.5</td>
<td>0.5</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td></td>
<td>25°C</td>
<td>-0.5 ±0.125</td>
<td>0.5</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td></td>
<td>-20°C</td>
<td>-0.5</td>
<td>0.5</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td></td>
<td>-30°C</td>
<td>-0.5625</td>
<td>0.5625</td>
<td>°C</td>
</tr>
<tr>
<td></td>
<td></td>
<td>-40°C</td>
<td>-0.625</td>
<td>0.625</td>
<td>°C</td>
</tr>
<tr>
<td>Temperature accuracy (1)(2)</td>
<td>VP – VN of 2.15 V to 5.5 V</td>
<td>-50°C</td>
<td>-0.6875 ±0.4</td>
<td>0.6875</td>
<td>°C</td>
</tr>
<tr>
<td>PULSE COUNT TRANSFER FUNCTION</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Number of pulses at 0°C</td>
<td></td>
<td>800</td>
<td>808</td>
<td>816</td>
<td></td>
</tr>
<tr>
<td>Output pulse range</td>
<td>Theoretical max (exceeds device rating)</td>
<td>1</td>
<td>4095</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Resolution of one pulse</td>
<td></td>
<td>0.0625</td>
<td>°C</td>
<td></td>
<td></td>
</tr>
<tr>
<td>OUTPUT CURRENT</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>$I_{OL}$</td>
<td>Output current variation</td>
<td>Low level</td>
<td>28</td>
<td>34</td>
<td>40</td>
</tr>
<tr>
<td>$I_{OH}$</td>
<td>High level</td>
<td>112.5</td>
<td>125</td>
<td>143</td>
<td>µA</td>
</tr>
<tr>
<td>High-to-Low level output current ratio</td>
<td></td>
<td>3.1</td>
<td>3.7</td>
<td>4.5</td>
<td></td>
</tr>
<tr>
<td>POWER SUPPLY</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Accuracy sensitivity to change in VP – VN</td>
<td>2.15 V ≤ VP – VN ≤ 5.0 V(3)</td>
<td>40</td>
<td>133</td>
<td>m°C/V</td>
<td></td>
</tr>
<tr>
<td>Leakage Current VP – VN</td>
<td>VDD ≤ 0.4 V</td>
<td>0.002</td>
<td>3.5</td>
<td>µA</td>
<td></td>
</tr>
<tr>
<td>THERMAL RESPONSE</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Stirred oil thermal response time to 63% of final value (package only)</td>
<td>DOX (WSON)</td>
<td>0.4</td>
<td>s</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>LPG (TO-92)</td>
<td>0.8</td>
<td>s</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Still air thermal response time to 63% of final value (package only)</td>
<td>DOX (WSON)</td>
<td>9.4</td>
<td>s</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>LPG (TO-92)</td>
<td>28</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

(1) Calculated using Pulse Count to Temperature LUT and 0.0625°C resolution per pulse, see section Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT and Electrical Characteristics - WSON/DOX Pulse Count to Temperature LUT.
(2) Error can be linearly interpolated between temperatures given in table as shown in the Accuracy vs Temperature curves in section Typical Characteristics.
(3) Limit is using end point calculation.
6.6 Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT

Over operating free-air temperature range and VP-VN operating range (unless otherwise noted). LUT is short for Look-up Table.

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>–50°C</td>
<td></td>
<td>15</td>
<td>26</td>
<td>37</td>
<td>pulses</td>
</tr>
<tr>
<td>–40°C</td>
<td></td>
<td>172</td>
<td>181</td>
<td>190</td>
<td></td>
</tr>
<tr>
<td>–30°C</td>
<td></td>
<td>329</td>
<td>338</td>
<td>347</td>
<td></td>
</tr>
<tr>
<td>–20°C</td>
<td></td>
<td>486</td>
<td>494</td>
<td>502</td>
<td></td>
</tr>
<tr>
<td>–10°C</td>
<td></td>
<td>643</td>
<td>651</td>
<td>659</td>
<td></td>
</tr>
<tr>
<td>0°C</td>
<td></td>
<td>800</td>
<td>808</td>
<td>816</td>
<td></td>
</tr>
<tr>
<td>10°C</td>
<td></td>
<td>958</td>
<td>966</td>
<td>974</td>
<td></td>
</tr>
<tr>
<td>20°C</td>
<td></td>
<td>1117</td>
<td>1125</td>
<td>1133</td>
<td></td>
</tr>
<tr>
<td>30°C</td>
<td></td>
<td>1276</td>
<td>1284</td>
<td>1292</td>
<td></td>
</tr>
<tr>
<td>40°C</td>
<td></td>
<td>1435</td>
<td>1443</td>
<td>1451</td>
<td></td>
</tr>
<tr>
<td>50°C</td>
<td></td>
<td>1594</td>
<td>1602</td>
<td>1610</td>
<td></td>
</tr>
<tr>
<td>60°C</td>
<td></td>
<td>1754</td>
<td>1762</td>
<td>1770</td>
<td></td>
</tr>
<tr>
<td>70°C</td>
<td></td>
<td>1915</td>
<td>1923</td>
<td>1931</td>
<td></td>
</tr>
<tr>
<td>80°C</td>
<td></td>
<td>2076</td>
<td>2084</td>
<td>2092</td>
<td></td>
</tr>
<tr>
<td>90°C</td>
<td></td>
<td>2237</td>
<td>2245</td>
<td>2253</td>
<td></td>
</tr>
<tr>
<td>100°C</td>
<td></td>
<td>2398</td>
<td>2407</td>
<td>2416</td>
<td></td>
</tr>
<tr>
<td>110°C</td>
<td></td>
<td>2560</td>
<td>2569</td>
<td>2578</td>
<td></td>
</tr>
<tr>
<td>120°C</td>
<td></td>
<td>2721</td>
<td>2731</td>
<td>2741</td>
<td></td>
</tr>
<tr>
<td>130°C</td>
<td></td>
<td>2883</td>
<td>2893</td>
<td>2903</td>
<td></td>
</tr>
<tr>
<td>140°C</td>
<td></td>
<td>3047</td>
<td>3057</td>
<td>3067</td>
<td></td>
</tr>
<tr>
<td>150°C</td>
<td></td>
<td>3208</td>
<td>3218</td>
<td>3228</td>
<td></td>
</tr>
</tbody>
</table>
6.7 Electrical Characteristics - WSON/DQX Pulse Count to Temperature LUT

Over operating free-air temperature range and 2.15 V ≤ VP – VN ≤ 5.0 V power supply operating range (unless otherwise noted). LUT is short for Look-up Table.

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Digital output code</td>
<td>–50°C</td>
<td>15</td>
<td>26</td>
<td>37</td>
<td>pulses</td>
</tr>
<tr>
<td></td>
<td>–40°C</td>
<td>172</td>
<td>181</td>
<td>190</td>
<td></td>
</tr>
<tr>
<td></td>
<td>–30°C</td>
<td>328</td>
<td>337</td>
<td>346</td>
<td></td>
</tr>
<tr>
<td></td>
<td>–20°C</td>
<td>486</td>
<td>494</td>
<td>502</td>
<td></td>
</tr>
<tr>
<td></td>
<td>–10°C</td>
<td>643</td>
<td>651</td>
<td>659</td>
<td></td>
</tr>
<tr>
<td></td>
<td>0°C</td>
<td>800</td>
<td>808</td>
<td>816</td>
<td></td>
</tr>
<tr>
<td></td>
<td>10°C</td>
<td>958</td>
<td>966</td>
<td>974</td>
<td></td>
</tr>
<tr>
<td></td>
<td>20°C</td>
<td>1117</td>
<td>1125</td>
<td>1133</td>
<td></td>
</tr>
<tr>
<td></td>
<td>30°C</td>
<td>1276</td>
<td>1284</td>
<td>1292</td>
<td></td>
</tr>
<tr>
<td></td>
<td>40°C</td>
<td>1435</td>
<td>1443</td>
<td>1451</td>
<td></td>
</tr>
<tr>
<td></td>
<td>50°C</td>
<td>1594</td>
<td>1603</td>
<td>1611</td>
<td></td>
</tr>
<tr>
<td></td>
<td>60°C</td>
<td>1754</td>
<td>1762</td>
<td>1771</td>
<td></td>
</tr>
<tr>
<td></td>
<td>70°C</td>
<td>1915</td>
<td>1923</td>
<td>1931</td>
<td></td>
</tr>
<tr>
<td></td>
<td>80°C</td>
<td>2076</td>
<td>2084</td>
<td>2092</td>
<td></td>
</tr>
<tr>
<td></td>
<td>90°C</td>
<td>2237</td>
<td>2245</td>
<td>2254</td>
<td></td>
</tr>
<tr>
<td></td>
<td>100°C</td>
<td>2398</td>
<td>2407</td>
<td>2416</td>
<td></td>
</tr>
<tr>
<td></td>
<td>110°C</td>
<td>2560</td>
<td>2569</td>
<td>2578</td>
<td></td>
</tr>
<tr>
<td></td>
<td>120°C</td>
<td>2721</td>
<td>2731</td>
<td>2741</td>
<td></td>
</tr>
<tr>
<td></td>
<td>125°C</td>
<td>2802</td>
<td>2814</td>
<td>2826</td>
<td></td>
</tr>
<tr>
<td></td>
<td>130°C</td>
<td>2883</td>
<td>2894</td>
<td>2904</td>
<td></td>
</tr>
<tr>
<td></td>
<td>140°C</td>
<td>3047</td>
<td>3058</td>
<td>3068</td>
<td></td>
</tr>
<tr>
<td></td>
<td>150°C</td>
<td>3210</td>
<td>3221</td>
<td>3231</td>
<td></td>
</tr>
</tbody>
</table>

6.8 Switching Characteristics

Over operating free-air temperature range and operating VP – VN range (unless otherwise noted).

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>tR, tF</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td>µs</td>
</tr>
<tr>
<td>Output current rise and fall time</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>CL = 10 pF, RL = 8 k</td>
<td>1.45</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>fP</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td>kHz</td>
</tr>
<tr>
<td>Output current pulse frequency</td>
<td>82</td>
<td>88</td>
<td>94</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Output current duty cycle</td>
<td>40%</td>
<td>50%</td>
<td>60%</td>
<td></td>
<td></td>
</tr>
<tr>
<td>tCONV</td>
<td>Temperature conversion time(1)</td>
<td>46</td>
<td>50</td>
<td>54</td>
<td>ms</td>
</tr>
<tr>
<td>tDATA</td>
<td>Data transmission time</td>
<td>44</td>
<td>47</td>
<td>50</td>
<td>ms</td>
</tr>
</tbody>
</table>

(1) Conversion time includes power up time or device turn on time that is typically 3 ms after POR threshold of 1.2 V is exceeded.
6.9 Timing Diagram

Figure 1. Timing Specification Waveform
6.10 Typical Characteristics

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 2.15 V

Figure 2. Accuracy vs LMT01 Junction Temperature

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 2.4 V

Figure 3. Accuracy vs LMT01 Junction Temperature

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 2.7 V

Figure 4. Accuracy vs LMT01 Junction Temperature

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 3 V

Figure 5. Accuracy vs LMT01 Junction Temperature

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 4 V

Figure 6. Accuracy vs LMT01 Junction Temperature

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 5 V

Figure 7. Accuracy vs LMT01 Junction Temperature
Typical Characteristics (continued)

<table>
<thead>
<tr>
<th>Frequency Accuracy (°C)</th>
<th>C022</th>
<th>-1</th>
<th>+1</th>
<th>0</th>
</tr>
</thead>
<tbody>
<tr>
<td>Max Limit</td>
<td>0.5625° C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Min Limit</td>
<td>-0.5625° C</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Frequency Accuracy (°C)</th>
<th>C021</th>
<th>-1</th>
<th>+1</th>
<th>0</th>
</tr>
</thead>
<tbody>
<tr>
<td>Max Limit</td>
<td>-0.5° C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Min Limit</td>
<td>-0.5° C</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Frequency Accuracy (°C)</th>
<th>C024</th>
<th>-1</th>
<th>+1</th>
<th>0</th>
</tr>
</thead>
<tbody>
<tr>
<td>Max Limit</td>
<td>0.5° C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Min Limit</td>
<td>-0.5° C</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Frequency Accuracy (°C)</th>
<th>C023</th>
<th>-1</th>
<th>+1</th>
<th>0</th>
</tr>
</thead>
<tbody>
<tr>
<td>Max Limit</td>
<td>0.5° C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Min Limit</td>
<td>-0.5° C</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Frequency Accuracy (°C)</th>
<th>C025</th>
<th>-1</th>
<th>+1</th>
<th>0</th>
</tr>
</thead>
<tbody>
<tr>
<td>Max Limit</td>
<td>0.625° C</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Min Limit</td>
<td>-0.625° C</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

---

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 5.5 V

Figure 8. Accuracy vs LMT01 Junction Temperature

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 2.15 V to 5.5 V

Figure 9. Accuracy Histogram at 150°C

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 2.15 V to 5.5 V

Figure 10. Accuracy Histogram at 30°C

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 2.15 V to 5.5 V

Figure 11. Accuracy Histogram at -20°C

Using LUT Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 2.15 V to 5.5 V

Figure 12. Accuracy Histogram at -30°C

Using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 2.15 V to 5.5 V

Figure 13. Accuracy Histogram at -40°C
Typical Characteristics (continued)

Using LUT Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT
VP – VN = 2.15 V to 5.5 V

Figure 14. Accuracy Histogram at -50°C

Using Temp = (PC/4096 × 256°C) – 50°C
VP – VN = 2.15 V

Figure 15. Accuracy Using Linear Transfer Function

Using Temp = (PC/4096 × 256°C) – 50°C
VP – VN = 5.5 V

TA = 30°C

Figure 16. Accuracy Using Linear Transfer Function

Figure 17. Output Current vs VP-VN Voltage

VP – VN = 3.3 V

Figure 18. Output Current vs Temperature

Figure 19. Thermal Response in Still Air (TO92S/LPG Package)
Typical Characteristics (continued)

Figure 20. Thermal Response in Moving Air (TO92S/LPG Package)

Figure 21. Thermal Response in Stirred Oil (TO92S/LPG Package)

VP – VN = 3.3 V
T\text{ INITIAL} = 23°C, \quad T\text{ FINAL} = 70°C

Air Flow = 2.34 meters/sec

VP – VN = 3.3 V
T\text{ INITIAL} = 23°C, \quad T\text{ FINAL} = 70°C
7 Detailed Description

7.1 Overview
The LMT01 temperature output is transmitted over a single wire using a train of current pulses that typically change from 34 µA to 125 µA. A simple resistor can then be used to convert the current pulses to a voltage. With a 10-kΩ resistor, the output voltage levels range from 340 mV to 1.25 V, typically. A simple microcontroller comparator or external transistor can be used convert this signal to valid logic levels the microcontroller can process properly through a GPIO pin. The temperature can be determined by gating a simple counter on for a specific time interval to count the total number of output pulses. After power is first applied to the device the current level will remain below 34 µA for at most 54 ms while the LMT01 is determining the temperature. When the temperature is determined, the pulse train begins. The individual pulse frequency is typically 88 kHz. The LMT01 will continuously convert and transmit data when the power is applied approximately every 104 ms (maximum).

The LMT01 uses thermal diode analog circuitry to detect the temperature. The temperature signal is then amplified and applied to the input of a ΣΔ ADC that is driven by an internal reference voltage. The ΣΔ ADC output is then processed through the interface circuitry into a digital pulse train. The digital pulse train is then converted to a current pulse train by the output signal conditioning circuitry that includes high and low current regulators. The voltage applied across the pins of the LMT01 is regulated by an internal voltage regulator to provide a consistent Chip V\text{DD} that is used by the ADC and its associated circuitry.

7.2 Functional Block Diagram

7.3 Feature Description

7.3.1 Output Interface
The LMT01 provides a digital output in the form of a pulse count that is transmitted by a train of current pulses. After the LMT01 is powered up, it transmits a very low current of 34 µA for less than 54 ms while the part executes a temperature to digital conversion, as shown in Figure 22. When the temperature-to-digital conversion is complete, the LMT01 starts to transmit a pulse train that toggles from the low current of 34 µA to a high current level of 125 µA. The pulse train total time interval is at maximum 50 ms. The LMT01 transmits a series of pulses equivalent to the pulse count at a given temperature as described in Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT. After the pulse count has been transmitted the LMT01 current level will remain low for the remainder of the 50 ms. The total time for the temperature to digital conversion and the pulse train time interval is 104 ms (maximum). If power is continuously applied, the pulse train output will repeat start every 104 ms (maximum).
Feature Description (continued)

The LMT01 can be powered down at any time to conserve system power. Take care to ensure that a minimum power-down wait time of 50 ms is used before the device is turned on again.

7.3.2 Output Transfer Function

The LMT01 outputs at minimum 1 pulse and a theoretical maximum 4095 pulses. Each pulse has a weight of 0.0625°C. One pulse corresponds to a temperature less than –50°C while a pulse count of 4096 corresponds to a temperature greater than 200°C. Note that the LMT01 is only ensured to operate up to 150°C. Exceeding this temperature by more than 5°C may damage the device. The accuracy of the device degrades as well when 150°C is exceeded.

Two different methods of converting the pulse count to a temperature value are discussed in this section. The first method is the least accurate and uses a first order equation, and the second method is the most accurate and uses linear interpolation of the values found in the look-up table (LUT) as described in Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT.

The output transfer function appears to be linear and can be approximated by Equation 1:

\[
\text{Temp} = \left( \frac{\text{PC}}{4096} \times 256°C \right) - 50°C
\]

where

- PC is the Pulse Count
- Temp is the temperature reading

(1)

Table 1 shows some sample calculations using Equation 1.

<table>
<thead>
<tr>
<th>TEMPERATURE (°C)</th>
<th>NUMBER OF PULSES</th>
</tr>
</thead>
<tbody>
<tr>
<td>–49.9375</td>
<td>1</td>
</tr>
<tr>
<td>–49.875</td>
<td>2</td>
</tr>
<tr>
<td>–40</td>
<td>160</td>
</tr>
<tr>
<td>–20</td>
<td>480</td>
</tr>
<tr>
<td>0</td>
<td>800</td>
</tr>
<tr>
<td>30</td>
<td>1280</td>
</tr>
<tr>
<td>50</td>
<td>1600</td>
</tr>
<tr>
<td>100</td>
<td>2400</td>
</tr>
<tr>
<td>150</td>
<td>3200</td>
</tr>
</tbody>
</table>
The curve shown in Figure 23 shows the output transfer function using equation Equation 1 (blue line) and the look-up table (LUT) found in Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT (red line). The LMT01 output transfer function as described by the LUT appears to be linear, but upon close inspection, it can be seen as truly not linear. To actually see the difference, the accuracy obtained by the two methods must be compared.

Figure 23. LMT01 Output Transfer Function

For more exact temperature readings the output pulse count can be converted to temperature using linear interpolation of the values found in Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT.

The curves in Figure 24 and Figure 25, show the accuracy of typical units when using the Equation 1 and linear interpolation using Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT, respectively. When compared, the improved performance when using the LUT linear interpolation method can clearly be seen. For a limited temperature range of 25°C to 80°C, the error shown in Figure 24 is flat, so the linear equation will provide good results. For a wide temperature range, TI recommends that linear interpolation and the LUT be used.

Figure 24. LMT01 Typical Accuracy When Using First Order Equation Equation 1 – 92 Typical Units Plotted at (VP – VN) = 2.15 V

Figure 25. LMT01 Accuracy Using Linear Interpolation of LUT Found In Electrical Characteristics - TO-92/LPG Pulse Count to Temperature LUT – 92 typical units plotted at (VP – VN) = 2.15 V

7.3.3 Current Output Conversion to Voltage

The minimum voltage drop across the LMT01 must be maintained at 2.15 V during the conversion cycle. After the conversion cycle, the minimum voltage drop can decrease to 2.0 V. Thus the LMT01 can be used for low voltage applications. See Application Information for more information on low voltage operation and other information on picking the actual resistor value for different applications conditions. The resistor value is dependent on the power supply level and the variation and the threshold level requirements of the circuitry the resistor is driving (that is, MCU, GPIO, or Comparator).
Stray capacitance can be introduced when connecting the LMT01 through a long wire. This stray capacitance influences the signal rise and fall times. The wire inductance has negligible effect on the AC signal integrity. A simple RC time constant model as shown in Figure 26 can be used to determine the rise and fall times.

\[
t_{\text{HL}} = R \times C \times \ln \left( \frac{V_F - V_S}{V_F - V_{\text{HL}}} \right)
\]

where
- RC as shown in Figure 26
- \( V_{\text{HL}} \) is the target high level
- the final voltage \( V_F = 125 \, \mu A \times R \)
- the start voltage \( V_S = 34 \, \mu A \times R \) \hspace{1cm} (2)

For the 10% to 90% level rise time (\( t_r \)), Equation 2 simplifies to:

\[
t_r = R \times C \times 2.197
\]

For the 10% to 90% level rise time (\( t_r \)), Equation 2 simplifies to:

\[
t_r = R \times C \times 2.197
\]

Take care to ensure that the LMT01 voltage drop does not exceed 300 mV under reverse bias conditions, as given in the Absolute Maximum Ratings.

### 7.4 Device Functional Modes

The only functional mode the LMT01 has is that it provides a pulse count output that is directly proportional to temperature.
8 Application and Implementation

NOTE
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’s customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

8.1.1 Mounting, Temperature Conductivity, and Self-Heating

The LMT01 can be applied easily in the same way as other integrated-circuit temperature sensors. It can be glued or cemented to a surface to ensure good temperature conductivity. The temperatures of the lands and traces to the leads of the LMT01 also affect the temperature reading, so they must be as thin as possible.

Alternatively, the LMT01 can be mounted inside a sealed-end metal tube, and then can be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the LMT01 and accompanying wiring and circuits must be kept insulated and dry to avoid excessive leakage and corrosion. Printed-circuit coatings are often used to ensure that moisture cannot corrode the leads or circuit traces.

The junction temperature of the LMT01 is the actual temperature being measured by the device. The thermal resistance junction-to-ambient ($R_{\text{θ JA}}$) is the parameter (from Thermal Information) used to calculate the rise of a device junction temperature (self-heating) due to its average power dissipation. The average power dissipation of the LMT01 is dependent on the temperature it is transmitting as it affects the output pulse count and the voltage across the device. Equation 4 is used to calculate the self-heating in the die temperature of the LMT01 ($T_{\text{SH}}$).

$$T_{\text{SH}} = \left[ \frac{I_{\text{OL}} \times t_{\text{CONV}}}{(t_{\text{CONV}} + t_{\text{DATA}})} \times V_{\text{CONV}} \right] + \left[ \frac{\text{PC} \times (I_{\text{OL}} + I_{\text{OH}})}{2} \right] + \left[ \frac{4096 - \text{PC}}{4096} \times I_{\text{OL}} \right] \times \frac{t_{\text{DATA}}}{(t_{\text{CONV}} + t_{\text{DATA}})} \times V_{\text{DATA}} \times R_{\text{θ JA}}$$

where

- $T_{\text{SH}}$ is the ambient temperature
- $I_{\text{OL}}$ and $I_{\text{OH}}$ are the output low and high current level, respectively
- $V_{\text{CONV}}$ is the voltage across the LMT01 during conversion
- $V_{\text{DATA}}$ is the voltage across the LMT01 during data transmission
- $t_{\text{CONV}}$ is the conversion time
- $t_{\text{DATA}}$ is the data transmission time
- PC is the output pulse count
- $R_{\text{θ JA}}$ is the junction to ambient package thermal resistance

Plotted in the curve Figure 27 are the typical average supply current (black line using left y axis) and the resulting self-heating (red and violet lines using right y axis) during continuous conversions. A temperature range of $-50^\circ\text{C}$ to $+150^\circ\text{C}$, a $V_{\text{CONV}}$ of 5 V (red line) and 2.15 V (violet line) were used for the self-heating calculation. As can be seen in the curve, the average power supply current and thus the average self-heating changes linearly over temperature because the number of pulses increases with temperature. A negligible self-heating of about 45m°C is observed at 150°C with continuous conversions. If temperature readings are not required as frequently as every 100 ms, self-heating can be minimized by shutting down power to the part periodically thus lowering the average power dissipation.
Application Information (continued)

8.2 Typical Application

8.2.1 3.3-V System VDD MSP430 Interface - Using Comparator Input

![Diagram of MSP430 Comparator Input Implementation]

Figure 28. MSP430 Comparator Input Implementation

8.2.1.1 Design Requirements

The design requirements listed in are used in the detailed design procedure.

<table>
<thead>
<tr>
<th>Table 2. Design Parameters</th>
</tr>
</thead>
<tbody>
<tr>
<td>DESIGN PARAMETER</td>
</tr>
<tr>
<td>VDD</td>
</tr>
<tr>
<td>VDD minimum</td>
</tr>
<tr>
<td>LMT01 VP – VN minimum during conversion</td>
</tr>
<tr>
<td>LMT01 VP – VN minimum during data transmission</td>
</tr>
<tr>
<td>Noise margin</td>
</tr>
<tr>
<td>Comparator input current over temperature range of interest</td>
</tr>
<tr>
<td>Resistor tolerance</td>
</tr>
</tbody>
</table>
8.2.1.2 Detailed Design Procedure

First, select the R and determine the maximum logic low voltage and the minimum logic high voltage while ensuring that when the LMT01 is converting, the minimum (VP − VN) requirement of 2.15 V is met.

1. Select R using minimum VP−VN during data transmission (2 V) and maximum output current of the LMT01 (143.75 µA)
   - R = (3.0 V − 2 V) / 143.75 µA = 6.993 k the closest 1% resistor is 6.980 k
   - 6.993 k is the maximum resistance so if using 1% tolerance resistor the actual resistor value needs to be 1% less than 6.993 k and 6.98 k is 0.2% less than 6.993 k thus 6.81 k must be used.

2. Check to see if the 2.15-V minimum voltage during conversion requirement for the LMT01 is met with the maximum I_{OL} of 39 µA and maximum R of 6.81 k + 1%:
   - V_{LMT01} = 3 V − (6.81 k × 1.01) × 39 µA = 2.73 V

3. Find the maximum low level voltage range using the maximum R of 6.81 k and maximum I_{OL} of 39 µA:
   - V_{RLmax} = (6.81 k × 1.01) × 39 µA = 268 mV

4. Find the minimum high level voltage using the minimum R of 6.81 k and minimum I_{OH} of 112.5 µA:
   - V_{RHmin} = (6.81 k × 0.99) × 112.5 µA = 758 mV

Now select the MSP430 comparator threshold voltage that enables the LMT01 to communicate to the MSP430 properly.

1. The MSP430 voltage is selected by selecting the internal V_{REF} and then choosing the appropriate 1 of n/32 settings for n of 1 to 31.
   - V_{MID} = (V_{RLmax} − V_{RHmin}) / 2 + V_{RHmin} = (758 mV − 268 mV) / 2 + 268 mV = 513 mV
   - n = (V_{MID} / V_{REF}) × 32 = (0.513 / 2.5) × 32 = 7

2. To prevent oscillation of the comparator, output hysteresis must be implemented. The MSP430 allows this by enabling different n for the rising edge and falling edge of the comparator output. For a falling comparator output transition, N must be set to 6.

3. Determine the noise margin caused by variation in comparator threshold level. Even though the comparator threshold level theoretically is set to V_{MID}, the actual level varies from device to device due to V_{REF} tolerance, resistor divider tolerance, and comparator offset. For proper operation, the COMP_B worst case input threshold levels must be within the minimum high and maximum low voltage levels presented across R, V_{RHmin} and V_{RLmax}, respectively

\[
V_{CHmax} = V_{REF} \times (1 + V_{\text{REF}_\text{TOL}}) \times \left(\frac{N + N_{\text{TOL}}}{32}\right) + \text{COMP\_OFFSET}
\]

where
- VREF is the MSP430 COMP_B reference voltage for this example at 2.5 V
- V_{\text{REF}_\text{TOL}} is the tolerance of the VREF of 1% or 0.01,
- N is the divisor for the MSP430 or 7
- N_{TOL} is the tolerance of the divisor or 0.5
- COMP\_OFFSET is the comparator offset specification or 10 mV

\[
V_{CLmin} = V_{REF} \times (1 - V_{\text{REF}_\text{TOL}}) \times \left(\frac{N - N_{\text{TOL}}}{32}\right) - \text{COMP\_OFFSET}
\]

where
- VREF is the MSP430 COMP_B reference voltage for this example at 2.5 V,
- V_{\text{REF}_\text{TOL}} is the tolerance of the VREF of 1% or 0.01,
- N is the divisor for the MSP430 for the hysteresis setting or 6,
- N_{TOL} is the tolerance of the divisor or 0.5,
- COMP\_OFFSET is the comparator offset specification or 10 mV

The noise margin is the minimum of the two differences:
(\text{V}_{RHmin} - V_{CHmax}) or (\text{V}_{CHmin} - V_{RLmax})

which works out to be 145 mV.
8.2.1.2.1 Setting the MSP430 Threshold and Hysteresis

The comparator hysteresis determines the noise level that the signal can support without causing the comparator to trip falsely and resulting in an inaccurate pulse count. The comparator hysteresis is set by the precision of the MSP430 and what thresholds it is capable of. For this case, as the input signal transitions high, the comparator threshold is dropped by 77 mV. If the noise on the signal is kept below this level as it transitions, the comparator will not trip falsely. In addition, the MSP430 has a digital filter on the COMP_B output that be used to further filter output transitions that occur too quickly.

8.2.1.3 Application Curves

8.3 System Examples

The LMT01 device can be configured in a number of ways. Transistor level shifting can be used so that the output pulse of the device can be read with a GPIO (see Figure 32). An isolation block can be inserted to achieve electrical isolation (see Figure 33). Multiple LMT01 devices can be controlled with GPIOs enabling temperature monitor for multiple zones. Lastly, the LMT01 device can be configured to have a common ground with a high side signal (see Figure 35).
System Examples (continued)

Figure 32. Transistor Level Shifting

Figure 33. Isolation

Figure 34. Connecting Multiple Devices to One MCU Input Pin

Note: to turn off an LMT01 set the GPIO pin connected to VP to high impedance state as setting it low would cause the off LMT01 to be reverse biased. Comparator input of MCU must be used.
System Examples (continued)

Note: the VN of the LMT01 must be connected to the MCU GND.

Figure 35. Common Ground With High-Side Signal

9 Power Supply Recommendations

Because the LMT01 is only a 2-pin device the power pins are common with the signal pins, thus the LMT01 has a floating supply that can vary greatly. The LMT01 has an internal regulator that provides a stable voltage to internal circuitry.

Take care to prevent reverse biasing of the LMT01 as exceeding the absolute maximum ratings may cause damage to the device.

Power supply ramp rate can effect the accuracy of the first result transmitted by the LMT01. As shown in Figure 36 with a 1-ms rise time, the LMT01 output code is at 1286, which converts to 30.125°C. The scope photo shown in Figure 37 reflects what happens when the rise time is too slow. In Figure 37, the power supply (yellow trace) is still ramping up to final value while the LMT01 (red trace) has already started a conversion. This causes the output pulse count to decrease from the previously shown 1286, to 1282 (or 29.875°C). Thus, for slow ramp rates, TI recommends that the first conversion be discarded. For even slower ramp rates, more than one conversion may have to be discarded as TI recommends that either the power supply be within final value before a conversion is used or that ramp rates be faster than 2.5 ms.

Figure 36. Output Pulse Count With Appropriate Power Supply Rise Time

Figure 37. Output Pulse Count With Slow Power Supply Rise Time
10 Layout

10.1 Layout Guidelines
The LMT01 can be mounted to a PCB as shown in Figure 38 and Figure 39. Take care to make the traces leading to the pads as small as possible to minimize their effect on the temperature the LMT01 is measuring.

10.2 Layout Example

![Layout Example (TO92S/LPG Package)](image)

Figure 38. Layout Example (TO92S/LPG Package)

![Layout Example for the DQX (WSON) Package](image)

Figure 39. Layout Example for the DQX (WSON) Package
11 Device and Documentation Support

11.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on Alert me to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.2 Community Resources

The following links connect to TI community resources. Linked contents are provided “AS IS” by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI’s views; see TI’s Terms of Use.

TI E2E™ Online Community TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support TI’s Design Support Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.3 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

11.4 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.5 Glossary

SLYZ022 — TI Glossary.
This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.
## PACKAGING INFORMATION

<table>
<thead>
<tr>
<th>Orderable Device</th>
<th>Status (1)</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>PIns</th>
<th>Package Qty</th>
<th>Eco Plan (2)</th>
<th>Lead/Ball Finish (6)</th>
<th>MSL Peak Temp (3)</th>
<th>Op Temp (°C)</th>
<th>Device Marking (4/5)</th>
<th>Samples</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMT01DQXR</td>
<td>ACTIVE</td>
<td>WSON</td>
<td>DQX</td>
<td>2</td>
<td>3000</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>SN</td>
<td>Level-1-260C-UNLIM</td>
<td>-50 to 150</td>
<td>13N</td>
<td>Samples</td>
</tr>
<tr>
<td>LMT01DQXT</td>
<td>ACTIVE</td>
<td>WSON</td>
<td>DQX</td>
<td>2</td>
<td>250</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>Call TI</td>
<td>Level-1-260C-UNLIM</td>
<td>-50 to 150</td>
<td>13N</td>
<td>Samples</td>
</tr>
<tr>
<td>LMT01LPG</td>
<td>ACTIVE</td>
<td>TO-92</td>
<td>LPG</td>
<td>2</td>
<td>1000</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>SN</td>
<td>N / A for Pkg Type</td>
<td>-50 to 150</td>
<td>LMT01</td>
<td>Samples</td>
</tr>
<tr>
<td>LMT01LPGM</td>
<td>ACTIVE</td>
<td>TO-92</td>
<td>LPG</td>
<td>2</td>
<td>3000</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>SN</td>
<td>N / A for Pkg Type</td>
<td>-50 to 150</td>
<td>LMT01</td>
<td>Samples</td>
</tr>
</tbody>
</table>

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBsolete: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

---

**Addendum-Page 1**
continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LMT01:

• Automotive: LMT01-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
### TAPE AND REEL INFORMATION

#### TAPE DIMENSIONS

- **A0**: Dimension designed to accommodate the component width
- **B0**: Dimension designed to accommodate the component length
- **K0**: Dimension designed to accommodate the component thickness
- **W**: Overall width of the carrier tape
- **P1**: Pitch between successive cavity centers

#### REEL DIMENSIONS

#### Quadrant Assignments for Pin 1 Orientation in Tape

*All dimensions are nominal*

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Reel Diameter (mm)</th>
<th>Reel Width W1 (mm)</th>
<th>A0 (mm)</th>
<th>B0 (mm)</th>
<th>K0 (mm)</th>
<th>P1 (mm)</th>
<th>W (mm)</th>
<th>Pin 1 Quadrant</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMT01DQXR</td>
<td>WSON</td>
<td>DQX</td>
<td>2</td>
<td>3000</td>
<td>180.0</td>
<td>8.4</td>
<td>2.0</td>
<td>2.8</td>
<td>1.0</td>
<td>4.0</td>
<td>8.0</td>
<td>Q1</td>
</tr>
<tr>
<td>LMT01DQXT</td>
<td>WSON</td>
<td>DQX</td>
<td>2</td>
<td>250</td>
<td>180.0</td>
<td>8.4</td>
<td>2.0</td>
<td>2.8</td>
<td>1.0</td>
<td>4.0</td>
<td>8.0</td>
<td>Q1</td>
</tr>
</tbody>
</table>

www.ti.com 23-May-2018
# TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal*

<table>
<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Length (mm)</th>
<th>Width (mm)</th>
<th>Height (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>LMT01DQXR</td>
<td>WSON</td>
<td>DQX</td>
<td>2</td>
<td>3000</td>
<td>203.0</td>
<td>203.0</td>
<td>35.0</td>
</tr>
<tr>
<td>LMT01DQXT</td>
<td>WSON</td>
<td>DQX</td>
<td>2</td>
<td>250</td>
<td>203.0</td>
<td>203.0</td>
<td>35.0</td>
</tr>
</tbody>
</table>
This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M
2. This drawing is subject to change without notice.
NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

4. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
NOTES:
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
EXAMPLE BOARD LAYOUT

TO-92 - 5.05 mm max height

LPG0002A

0.05 MAX ALL AROUND TYP

METAL TYP

3X (Ø 0.75) VIA

SOLDER MASK OPENING TYP

LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 20X

TO-92
IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2020, Texas Instruments Incorporated